physical. chemical. biological.

## FlipChip Series <br> FC platinum sensor

## For the automatic assembling on PCB by soldering or bonding

## Benefits \& Characteristics

- Excellent long-term stability
- Minimum space consumption on PCB
- Fast response time
- Low self-heating
|llustration ${ }^{1)}$
- Optimal price-performance ratio
- Bondable versions available
- Customer-specific sensor available upon request


H
L1
$+\square$

1) For actual size, see dimensions

Technical Data

| Operating temperature range: | 1FC | $-50^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$ |
| :---: | :---: | :---: |
|  | 2FC | $-50^{\circ} \mathrm{C}$ to $+250^{\circ} \mathrm{C}$ |
|  | 3FC | $-50^{\circ} \mathrm{C}$ to $+250^{\circ} \mathrm{C}$ |
|  | 5FC | $-50^{\circ} \mathrm{C}$ to $+400^{\circ} \mathrm{C}$ |
|  | 6FC | $-50^{\circ} \mathrm{C}$ to $+600^{\circ} \mathrm{C}$ |
| Nominal resistance:* | $100 \Omega$ at $0^{\circ} \mathrm{C}$ |  |
|  | $500 \Omega$ at $0^{\circ} \mathrm{C}$ |  |
|  | $1000 \Omega$ at $0^{\circ} \mathrm{C}$ |  |
| Characteristics curve:* | 3850 ppm/K |  |
| Long-term stability: | < 0.04 \% at 100 | $\mathrm{t}+130^{\circ} \mathrm{C}$ |
| Tolerance class (dependent on temperature range):* |  | IST AG reference |
|  | IEC 60751 F0.3 | B |
|  | IEC 60751 F0.6 | C |


| Connection:* | 1FC | tin-coated, LMP lead-free, $96.5 \mathrm{Sn} / 3 \mathrm{Ag} / 0.5 \mathrm{Cu}$ ) (reflow soldering) |
| :---: | :---: | :---: |
|  | 2FC | tin-coated, HMP soldering depot, $5 \mathrm{Sn} / 93.5 \mathrm{~Pb} / 1.5 \mathrm{Ag}$ (reflow soldering) |
|  | 3FC | Au-Pads (bonding pads), various types available |
|  | 5FC | reinforced thin-film Pt-pads (solderable pads) |
|  | 6FC | thick-film Pt-pads (weldable) |
| Solderability:1) | $235{ }^{\circ} \mathrm{C} \leq 8 \mathrm{~s}$ (DIN IEC 68 T2-20, Ta Meth. 1) - 1FC, 2FC, 5FC |  |
| 1) The soldering process can influence accuracy |  |  |
| Resistance to soldering heat: | $260{ }^{\circ} \mathrm{C} 10 \mathrm{~s}$ (DIN IEC 68 T2-20, Ta Meth. 1A) - 1FC, 2FC, 5FC |  |
| Recommended applied current: ${ }^{\text {2) }}$ | 1 mA at $100 \Omega$ |  |
| 2) Sel-heating must be considered | 0.5 mA at $500 \Omega$ |  |
|  | 0.3 mA at $1000 \Omega$ |  |
| Other alternatives:* | Metallized backside |  |
|  | Substrate thickness |  |
| Packaging: | < 100 pcs in trays |  |
|  | > 100 pcs taped on reel |  |
|  | > 100 pcs diced substrate on foil |  |

* Customer-specific alternatives available

Order Information - 1FC (Contacts tin-coated (96.5Sn/3Ag/0.5Cu), LMP lead-free)

Size Dimensions (L/L1/L2 $\times$ W / W1 $\times \mathrm{H}$ in mm) F0.3 (class B)

Packed in trays (< 100 pcs)

Nominal resistance: $100 \Omega$ at $0^{\circ} \mathrm{C}$

| $0603( \pm 0.2)$ | $1.5 / 0.25 / 0.9 \times 0.75 / 0.7 \times 0.45( \pm 0.15)$ | POK1.0603.1FC.B |
| :--- | :--- | :--- |
| Order code |  | 310.00655 |
| $0805( \pm 0.2)$ | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.45( \pm 0.15)$ | POK1.0805.1FC.B |
| Order code |  | 010.02586 |
|  |  |  |
| Nominal resistance: $500 \Omega$ at $0^{\circ} \mathrm{C}$ | POK5.0805.1FC.B |  |
| $0805( \pm 0.2)$ | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.45( \pm 0.15)$ | 010.02705 |

Nominal resistance: $1000 \Omega$ at $0^{\circ} \mathrm{C}$

| $0603( \pm 0.2)$ | $1.5 / 0.25 / 0.9 \times 0.75 / 0.7 \times 0.45( \pm 0.15)$ | P1K0.0603.1FC.B |
| :--- | :--- | :--- |
| Order code |  | 310.00656 |
| $0805( \pm 0.2)$ | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.45( \pm 0.15)$ | P1K0.0805.1FC.B |
| Order code |  | 010.02557 |

Taped on reel (> 100 pcs )

Nominal resistance: $500 \Omega$ at $0^{\circ} \mathrm{C}$

| $0805( \pm 0.2)$ | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.45( \pm 0.15)$ | POK5.0805.1FC.B.S |
| :--- | :--- | :--- |
| Order code | Sensor side down | 010.02706 |

Nominal resistance: $1000 \Omega$ at $0^{\circ} \mathrm{C}$

| $0805( \pm 0.2)$ | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.45( \pm 0.15)$ | P1K0.0805.1FC.B.S |
| :--- | :--- | :--- |
| Order code | Sensor side down | 010.02558 |

Diced substrate on foil (> 100 pcs)

Nominal resistance: $1000 \Omega$ at $0{ }^{\circ} \mathrm{C}$

| $0805( \pm 0.2)$ | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.45( \pm 0.15)$ | P1K0.0805.1FC.B.S |
| :--- | :--- | :--- |
| Order code |  | 010.02602 |

Order Information - 2FC (contacts tin-coated, soldering depot, HMP, 5Sn/93.5Pb/1.5Ag)

Available upon request

Order Information - 3FC (Au-Pads (bonding pads), various types available)

Size Dimensions (L/L1/L2 $\times \mathrm{W} / \mathrm{W} 1 \times \mathrm{H}$ in mm) F0.3 (class B)

Packed in trays (< 100 pcs)

Nominal resistance: $100 \Omega$ at $0^{\circ} \mathrm{C}$

| $0805( \pm 0.2)$ | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.4( \pm 0.15)$ | POK1.0805.3FC.B |
| :--- | :--- | :--- |
| Order code |  | 310.00536 |
| $1206( \pm 0.2)$ | $2.9 / 0.35 / 2.1 \times 1.4 / 1.3 \times 0.4( \pm 0.15)$ | POK1.1206.3FC.B |
| Order code |  | 310.00818 |

Nominal resistance: $1000 \Omega$ at $0^{\circ} \mathrm{C}$

| $0603( \pm 0.2)$ | $1.5 / 0.25 / 0.9 \times 0.75 / 0.7 \times 0.4( \pm 0.15)$ | P1K0.0603.3FC.B.S |
| :--- | :--- | :--- |
| Order code | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.4( \pm 0.15)$ | 310.00653 |
| $0805( \pm 0.2)$ | P1K0.0805.3FC.B |  |
| Order code | $1.6 \times 1.2 \times 0.25( \pm 0.15)$ | 010.02749 |
| 161 | P1K0.161.3FC.B |  |
| Order code |  | 010.01863 |

Size
Dimensions (L / L1 / L2 $\times \mathrm{W} / \mathrm{W} 1 \times \mathrm{H}$ in mm)
F0.3 (class B)

Diced substrate on foil (> 100 pcs)

| Nominal resistance: $100 \Omega$ at $0^{\circ} \mathrm{C}$ |  |
| :--- | :--- |
| 0805 | $1.9 / 0.25 / 1.4 \times 1.15 / 1.1 \times 0.4( \pm 0.15)$ |
| Order code | POK1.0805.3FC.B.S |

Order Information - 5FC (reinforced thin-film Pt-pads (solderable pads))

Available upon request

Order Information - 6FC (thick-film Pt-pads (weldable))
Size Dimensions (L L L1 / L2 $\times \mathrm{W} / \mathrm{W} 1 \times \mathrm{H}$ in mm) F0.3 (class B)

| Nominal resistance: $1000 \Omega$ at $0^{\circ} \mathrm{C}$ |  |  |
| :--- | :--- | :--- |
| 0805 | $2.0 / 0.525 / 0.8 \times 1.2 / 0.95 \times 0.45( \pm 0.15)$ | P1K0.0805.6FC.B.S |
|  |  | 310.01443 |
| 161 | $1.6 \times 1.2 \times 0.25( \pm 0.15)$ | P1K0.161.6FC.B |
| Order code |  | 010.00626 |

Additional Documents

Document name:
Application Note:
ATP_E

## Order Information <br> FC platinum sensor Secondary reference

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Material
P = Platinum
(1)FC \(=\) tin-coated, LMP lead-free, \(6.5 \mathrm{Sn} / 3 \mathrm{Ag} / 0.5 \mathrm{Cu})\)
(2)FC \(=\) tin-coated, soldering depot, HMP, 5Sn/93.5Pb/1.5Ag
(3)FC = Au-Pads (bonding pads), various types available
(5)FC \(=\) reinforced thin-film Pt-pads
(6)FC \(=\) thick-film Pt-pads

Tolerance class

B.

S
\(1=-50^{\circ} \mathrm{C}\) to \(+150^{\circ} \mathrm{C} \quad 5=-50^{\circ} \mathrm{C}\) to \(+400^{\circ} \mathrm{C}\)
\(2=-50^{\circ} \mathrm{C}\) to \(+250^{\circ} \mathrm{C} \quad 6=-50^{\circ} \mathrm{C}\) to \(+600^{\circ} \mathrm{C}\)
\(3=-50^{\circ} \mathrm{C}\) to \(+250^{\circ} \mathrm{C}\)```

